

DESCRIPTION:

The DPS128X24Bn3 High Speed SRAM "STACK" modules are a revolutionary new memory subsystem using Dense-Pac Microsystems' ceramic Stackable Leadless Chip Carriers (SLCC). Available in straight leaded, "J" leaded or gullwing leaded packages, or mounted on a 50-pin PGA co-fired ceramic substrate. The module packs 3-Megabits of low-power CMOS static RAM in an area as small as 0.463 in², while maintaining a total height as low as 0.332 inches.

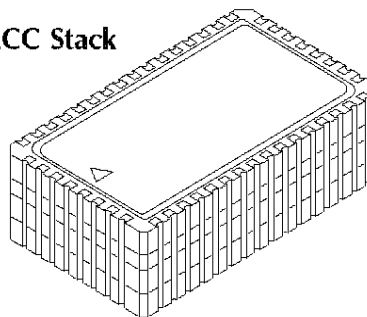
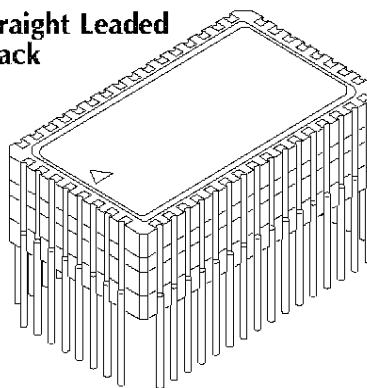
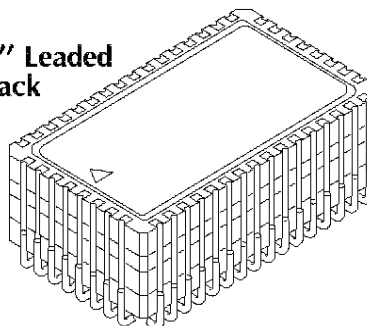
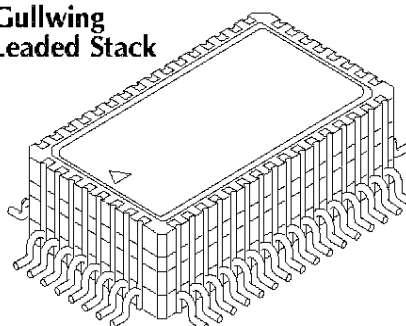
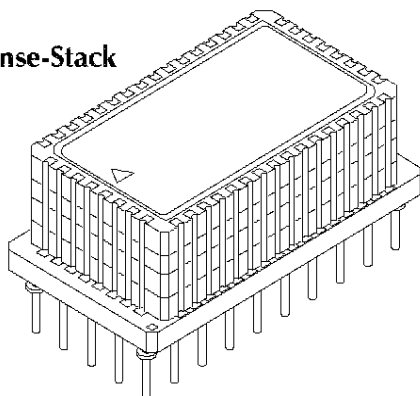
The DPS128X24Bn3 STACK modules contain three individual 128K x 8 SRAMs, each packaged in a hermetically sealed SLCC, making the modules suitable for commercial, industrial and military applications.

By using SLCCs, the "Stack" family of modules offer a higher board density of memory than available with conventional through-hole, surface mount or hybrid techniques.

FEATURES:

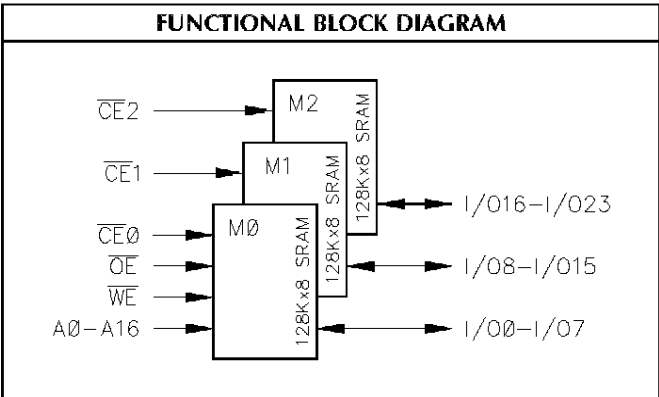
- Organizations Available: 128Kx24, 384Kx8
- Access Times: 20*, 25, 30, 35, 45ns
- Fully Static Operation - No clock or refresh required
- Single +5V Power Supply, $\pm 10\%$ Tolerance
- TTL Compatible
- Common Data Inputs and Outputs
- Low Data Retention Voltage: 2.0V min.
- Packages Available:
 - 48 - Pin SLCC Stack
 - 48 - Pin Straight Leaded Stack
 - 48 - Pin "J" Leaded Stack
 - 48 - Pin Gullwing Leaded Stack
 - 50 - Pin PGA Dense-Stack

* Commercial only.

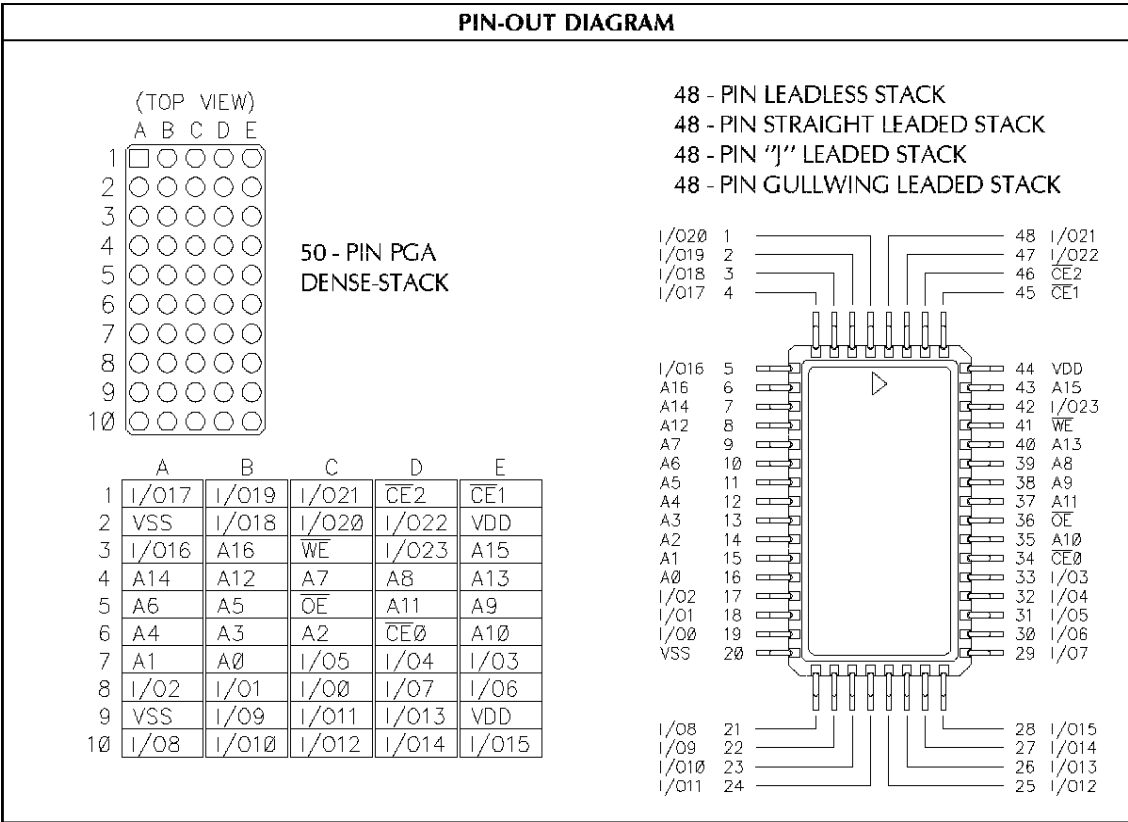
SLCC Stack**Straight Leaded Stack****"J" Leaded Stack****Gullwing Leaded Stack****Dense-Stack**

DPS128X24Bn3

Dense-Pac Microsystems, Inc.



PIN NAMES	
A0 - A16	Address Inputs
I/O0 - I/O23	Data Input/Output
CE0 - CE2	Low Chip Enables
WE	Write Enable
OE	Output Enable
VDD	Power (+ 5V)
Vss	Ground



ABSOLUTE MAXIMUM RATINGS ³			
Symbol	Parameter	Value	Unit
T _{STC}	Storage Temperature	-65 to +150	°C
T _{BIAS}	Temperature Under Bias	-55 to +125	°C
V _{DD}	Supply Voltage ¹	-0.5 to +7.0	°C
V _{I/O}	Input/Output Voltage ¹	-0.5 to V _{DD} + 0.5	V

TRUTH TABLE					
Mode	$\overline{CE}$	$\overline{WE}$	$\overline{OE}$	I/O Pin	Supply Current
Not Selected	H	X	X	High-Z	Standby
DOUT Disable	L	H	H	High-Z	Active
Read	L	H	L	D _{OUT}	Active
Write	L	L	X	D _{IN}	Active

H = HIGH

L = LOW

X = Don't Care

DC OUTPUT CHARACTERISTICS					
Symbol	Parameter	Conditions	Min.	Max.	Unit
V _{OH}	HIGH Voltage	I _{OH} = -4.0mA	2.4		V
V _{OL}	LOW Voltage	I _{OL} = 8.0mA		0.4	V

RECOMMENDED OPERATING RANGE ³					
Symbol	Characteristic	Min.	Typ.	Max.	Unit
V _{DD}	Supply Voltage	4.5	5.0	5.5	V
V _{IH}	Input HIGH Voltage	2.2		V _{DD} + 0.3	V
V _{IL}	Input LOW Voltage	-0.5 ²		0.8	V
T _A	Operating Temperature	M/B	-55	+25	+125
		I	-40	+25	+85
		C	0	+25	+70
					°C

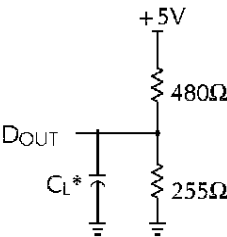
CAPACITANCE ⁴ : T _A = 25°C, F = 1.0MHz				
Symbol	Parameter	Max.	Unit	Condition
C _{ADR}	Address Input	35	pF	V _{IN} ² = 0V
C _{CE}	Chip Enable	15		
C _{WE}	Write Enable	35		
C _{OE}	Output Enable	35		
C _{I/O}	Data Input/Output	15		

DC OPERATING CHARACTERISTICS: Over operating ranges											
Symbol	Characteristics	Test Conditions		Typ.*	C		I		M/B		Unit
					Min.	Max.	Min.	Max.	Min.	Max.	
I _{IN}	Input Leakage Current	V _{IN} = 0V to V _{DD}		-	-15	+15	-15	+15	-15	+15	μA
I _{OUT}	Output Leakage Current	V _{I/O} = 0V to V _{DD} , $\overline{CE}$ or $\overline{OE}$ = V _{IH} , or $\overline{WE}$ = V _{IL}		-	-10	+10	-10	+10	-10	+10	μA
I _{CC}	Operating Supply Current	Cycle = min., Duty = 100% I _{OUT} = 0mA	x8	150		200		210		230	mA
			x24	300		420		420		480	
I _{SB1}	Full Standby Supply Current	V _{IN} ≥ V _{DD} -0.2V or V _{IN} ≤ V _{SS} +0.2V		1.2		15		15		30	mA
I _{SB2}	Standby Current (TTL)	$\overline{CE}$ = V _{IH}		75		90		105		105	mA
I _{DR3}	Data Retention Supply Current (3V)	V _{DR} = 3V, $\overline{CE}$ ≥ V _{DR} -0.2V		0.21		1.2		1.8		6.0	mA
I _{DR2}	Data Retention Supply Current (2V)	V _{DR} = 2V, $\overline{CE}$ ≥ V _{DR} -0.2V		.105		0.75		1.2		5.4	mA
V _{OL}	Output Low Voltage	I _{OUT} = 8.0mA		-		0.4		0.4		0.4	V
V _{OH}	Output High Voltage	I _{OUT} = -4.0mA		-	2.4		2.4		2.4		V

† Typical measurements made at +25°C, Cycle = min., V_{DD} = 5.0V.

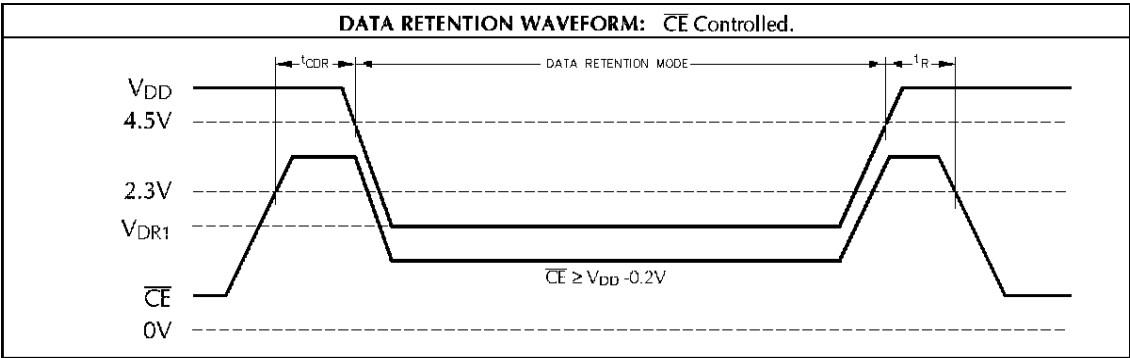
OUTPUT LOAD		
Load	C _L	Parameters Measured
1	30pF	except t _{LZ} , t _{HZ} , t _{OHZ} , t _{OLZ} , and t _{WHZ}
2	5pF	t _{LZ} , t _{HZ} , t _{OHZ} , t _{OLZ} , and t _{WHZ}

Figure 1. Output Load
* Including Probe and Jig Capacitance.



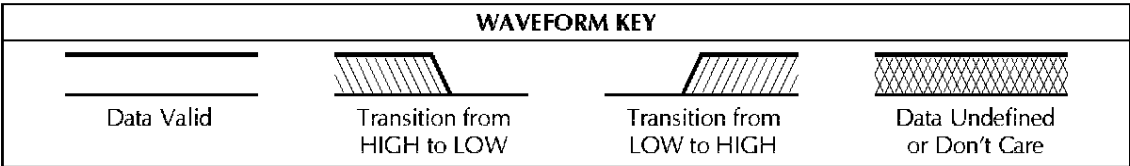
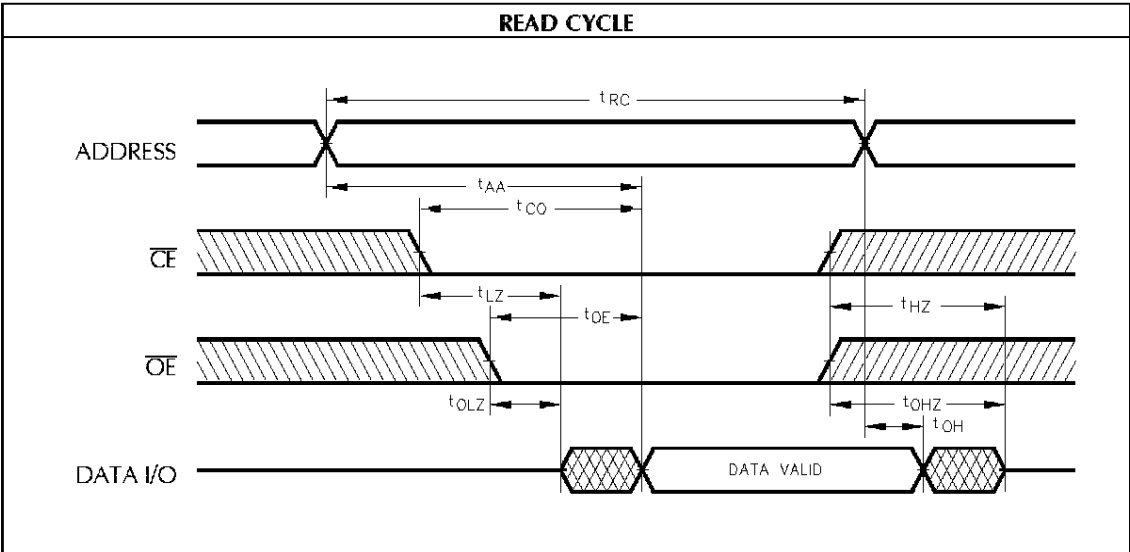
AC TEST CONDITIONS	
Input Pulse Levels	0V to 3.0V
Input Pulse Rise and Fall Times	5ns
Input and Output Timing Reference Levels	1.5V

Data Retention AC Characteristics ⁸						
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{DR}	V _{DD} for Data Retention	$\overline{CE} \geq V_{DR} - 0.2V$	2.0	-	-	V
V _{CDR}	Chip Disable to Data Retention Time	See Data Retention Waveform	0	-	-	ns
t _R	Operation Recovery Time	See Data Retention Waveform	5	-	-	ms



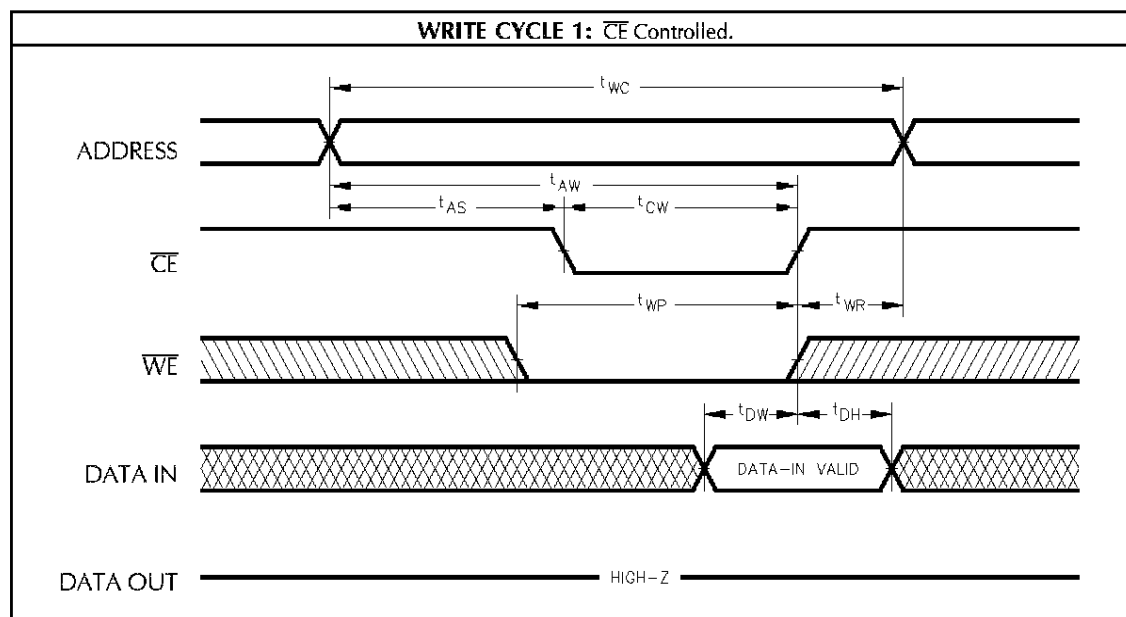
AC OPERATING CONDITIONS AND CHARACTERISTICS - READ CYCLE: Over operating ranges													
No.	Symbol	Parameter	20ns*		25ns		30ns		35ns		45ns		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
1	t _{RC}	Read Cycle Time	20		25		30		35		45		ns
2	t _{AA}	Address Access Time		20		25		30		35		45	ns
3	t _{CO}	$\overline{CE}$ to Output Valid		20		25		30		35		45	ns
4	t _{OE}	Output Enable to Output Valid		8		10		15		20		25	ns
5	t _{LZ}	$\overline{CE}$ to Output in LOW-Z ^{4, 5}	3		3		3		3		3		ns
6	t _{OLZ}	Output Enable to Output in LOW-Z ^{4, 5}	0		0		0		0		0		ns
7	t _{HZ}	$\overline{CE}$ to Output in HIGH-Z ^{4, 5}		10		12		15		20		25	ns
8	t _{OHZ}	Output Enable to Output in HIGH-Z ^{4, 5}		8		10		15		20		25	ns
9	t _{OH}	Output Hold from Address Change	3		3		3		3		3		ns

* Available in Commercial Only.



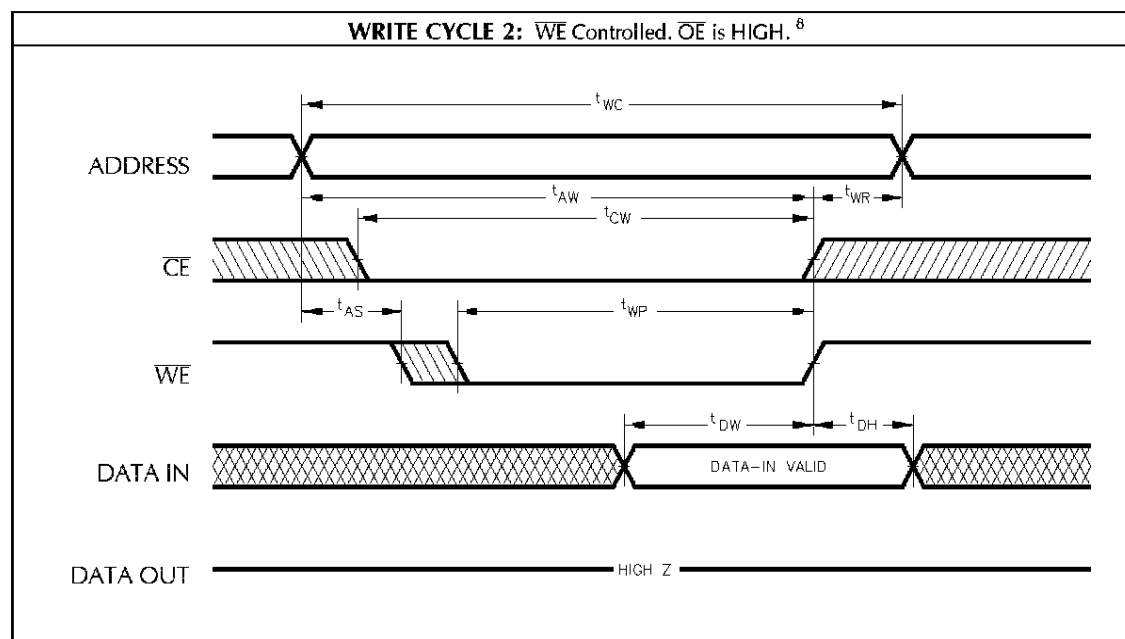
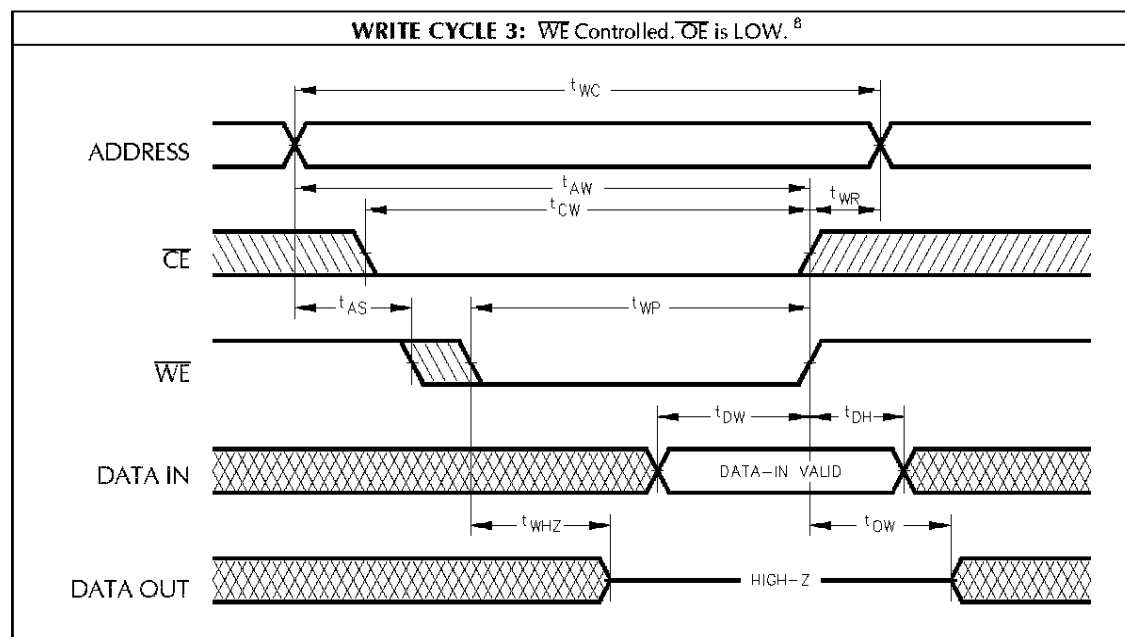
AC OPERATING CONDITIONS AND CHARACTERISTICS - WRITE CYCLE ^{6, 7} : Over operating ranges													
No.	Symbol	Parameter	20ns*		25ns		30ns		35ns		45ns		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
10	t _{WC}	Write Cycle Time	20		25		30		35		45		ns
11	t _{AW}	Address Valid to End of Write	15		20		25		30		40		ns
12	t _{CW}	Chip Enable to End of Write	15		20		25		30		40		ns
13	t _{AS}	Address Set-Up Time **	0		0		0		0		0		ns
14	t _{WP}	Write Pulse Width	15		20		25		30		35		ns
15	t _{WR}	Write Recovery Time	0		0		0		0		0		ns
16	t _{WHZ}	Write Enable to Output in HIGH-Z ^{4, 5}		8		10		12		15		20	ns
17	t _{DW}	Data to Write Time Overlap	12		15		15		20		25		ns
18	t _{DH}	Data Hold from Write Time	0		0		0		0		0		ns
19	t _{OW}	Output Active from End of Write	3		3		3		3		3		ns

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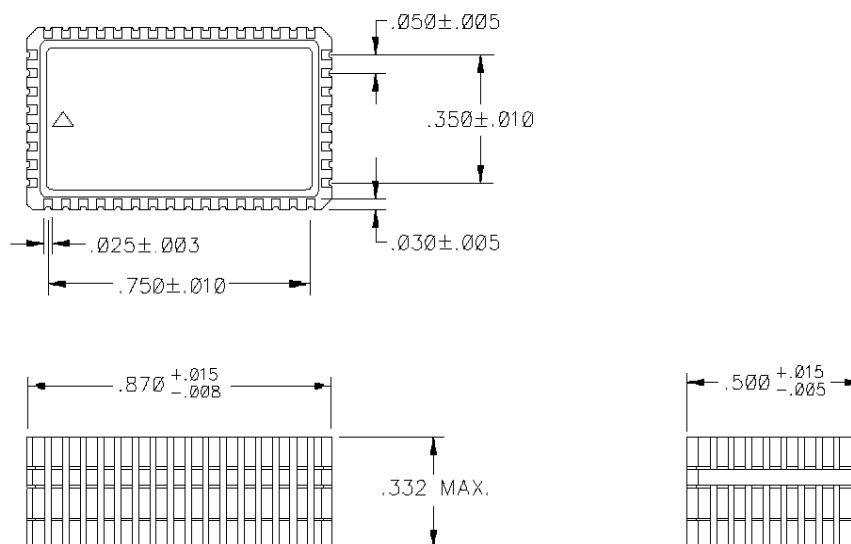


NOTES:

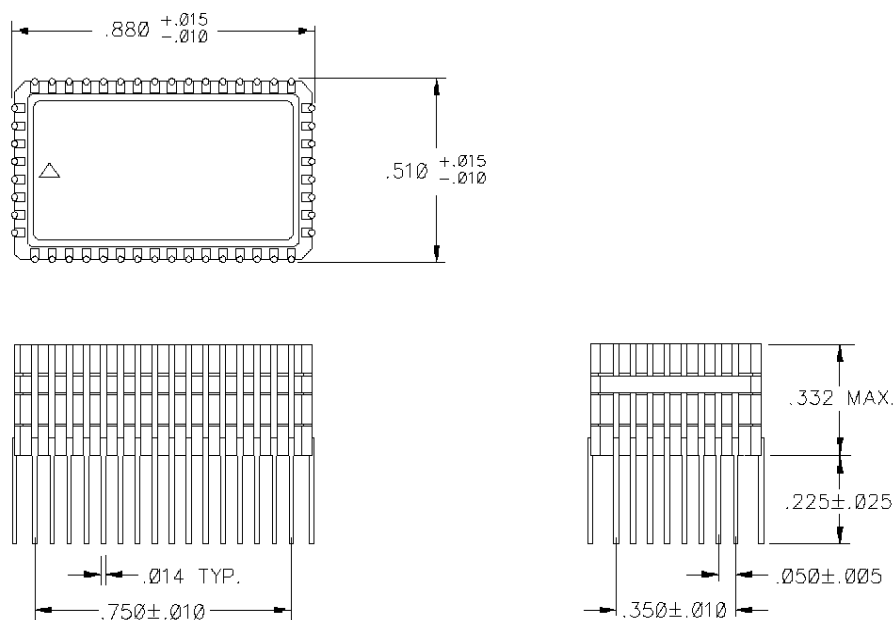
1. All voltages are with respect to V_{SS}.
2. -2.0V min. for pulse width less than 20ns (V_{IL} min. = -0.5V at DC level).
3. Stresses greater than those under **ABSOLUTE MAXIMUM RATINGS** may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
4. This parameter is guaranteed and not 100% tested.
5. Transition is measured at the point of $\pm 500\text{mV}$ from steady state voltage.
6. When $\overline{OE}$ and $\overline{CE}$ are LOW and $\overline{WE}$ is HIGH, I/O pins are in the output state, and input signals of opposite phase to the outputs must not be applied.
7. The outputs are in a high impedance state when $\overline{WE}$ is LOW.
8. Chip Enable and Write Enable can initiate and terminate WRITE Cycle.

WRITE CYCLE 2: $\overline{WE}$ Controlled, $\overline{OE}$ is HIGH.⁸**WRITE CYCLE 3: $\overline{WE}$ Controlled, $\overline{OE}$ is LOW.⁸**

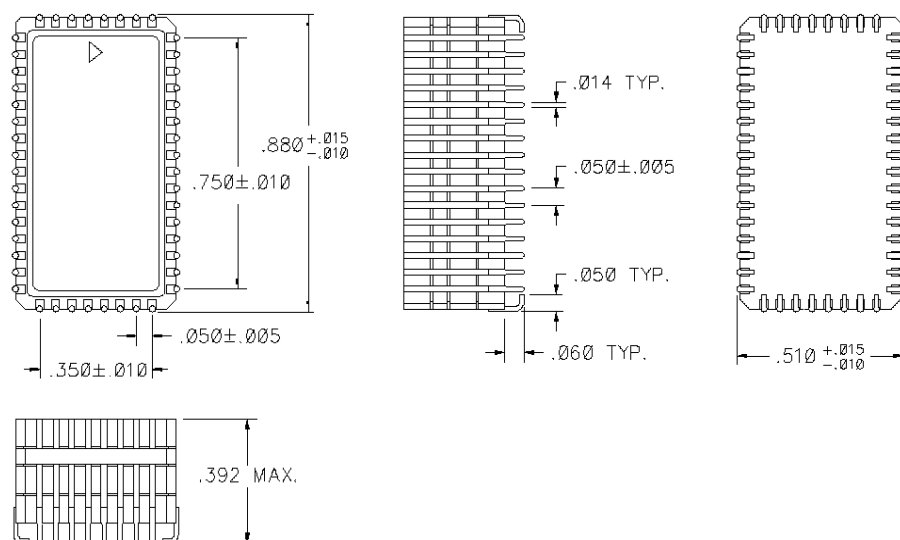
(48 - PIN LEADLESS STACK) MECHANICAL DRAWING



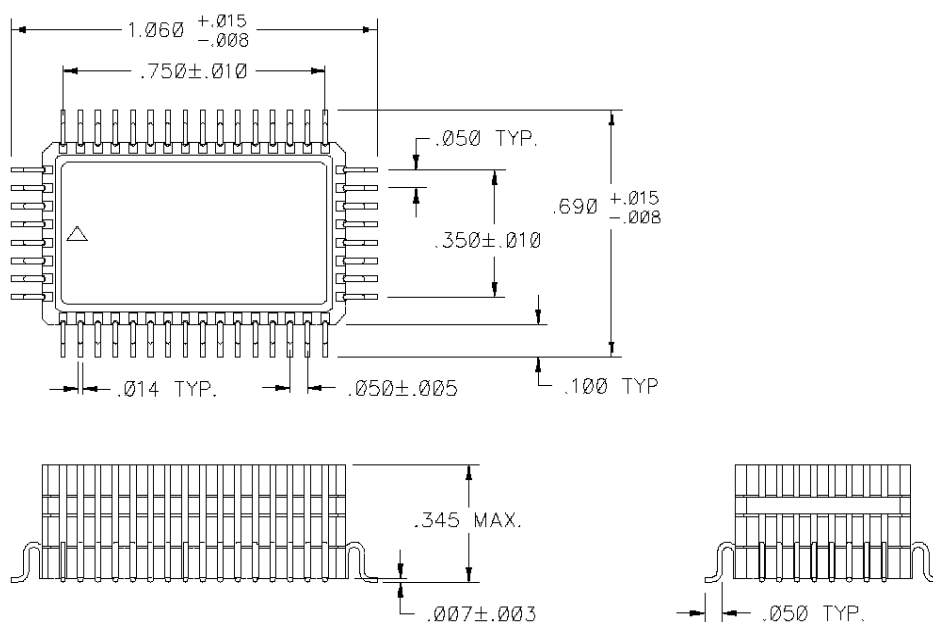
(48 - PIN STRAIGHT LEADED STACK) MECHANICAL DRAWING



(48 - PIN "J" LEADED STACK) MECHANICAL DRAWING

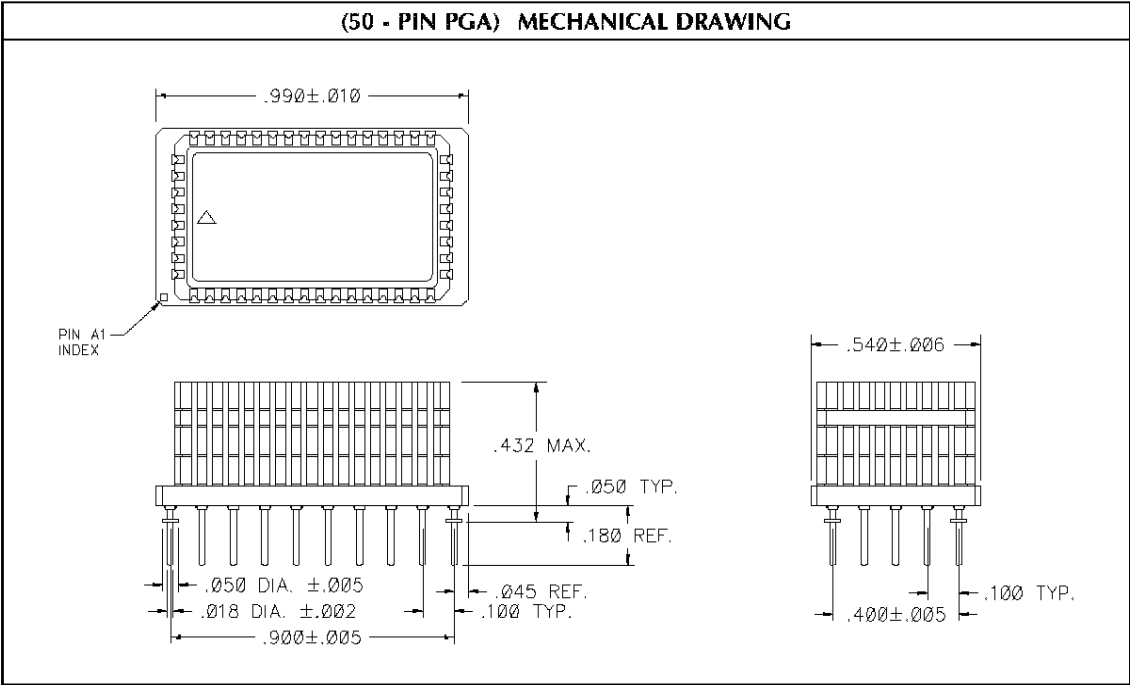


(48 - PIN GULLWING LEADED STACK) MECHANICAL DRAWING



DPS128X24Bn3

Dense-Pac Microsystems, Inc.



ORDERING INFORMATION									
DP	S	128	X	24	B	X3	-XX	X	
PREFIX	TYPE	MEMORY DEPTH	DESIG	MEMORY WIDTH	DESIG.	PACKAGE	SPEED	GRADE	
									C COMMERCIAL 0°C to +70°C
									I INDUSTRIAL -40°C to +85°C
									M MILITARY -55°C to +125°C
									B MIL-PROCESSED -55°C to +125°C
									20 20ns (COMMERCIAL ONLY)
									25 25ns
									30 30ns
									35 35ns
									45 45ns
									A3 DENSE-STACK PGA (PIN GRID ARRAY)
									H3 GULLWING LEADED SLCC STACK
									I3 THRU-HOLE LEADED SLCC STACK
									J3 "J" LEADED SLCC STACK
									Y3 LEADLESS SLCC STACK
									B HIGH SPEED / SINGLE CHIP ENABLE
									MODULE WITHOUT SUPPORT LOGIC
									CMOS SRAM DEVICES

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